

ABSTRACT OF THE DISCLOSURE

A package structure of OEL panel is composed of a printed circuit board, one or multiple OEL panels, and multiple bumps. Wherein, the OEL panel has multiple poly solder interconnection arranged in an array structure. The printed circuit board has multiple solder pads, and bumps are disposed on the solder pads. The one or more OEL panel are disposed on the printed circuit board with the electric coupling via the poly solder interconnections, so as to have the electric connection for the OEL panel and the printed circuit board.